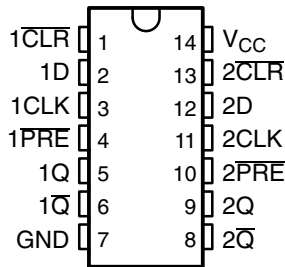


# SN54LV74A, SN74LV74A DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOPS

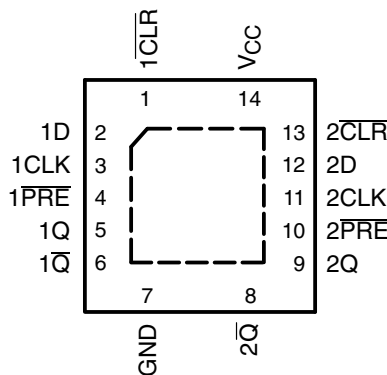
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- 2-V to 5.5-V  $V_{CC}$  Operation
- Max  $t_{pd}$  of 8.5 ns at 5 V
- Typical  $V_{OLP}$  (Output Ground Bounce)  $<0.8$  V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$
- Typical  $V_{OHV}$  (Output  $V_{OH}$  Undershoot)  $>2.3$  V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$
- Support Mixed-Mode Voltage Operation on All Ports
- $I_{off}$  Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

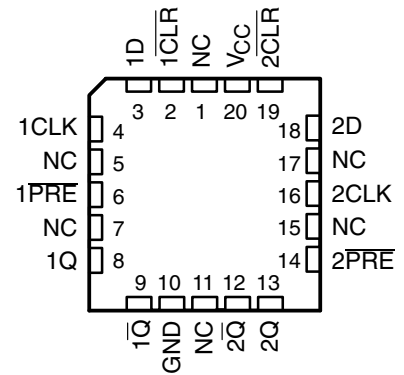
SN54LV74A . . . J OR W PACKAGE  
SN74LV74A . . . D, DB, DGV, NS,  
OR PW PACKAGE  
(TOP VIEW)



SN74LV74A . . . RGY PACKAGE  
(TOP VIEW)



SN54LV74A . . . FK PACKAGE  
(TOP VIEW)



NC – No internal connection

## description/ordering information

These dual positive-edge-triggered D-type flip-flops are designed for 2-V to 5.5-V  $V_{CC}$  operation.

## ORDERING INFORMATION

$T_A$	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	QFN – RGY	Reel of 1000	SN74LV74ARGYR	LV74A
	SOIC – D	Tube of 50	SN74LV74AD	LV74A
		Reel of 2500	SN74LV74ADR	
	SOP – NS	Reel of 2000	SN74LV74ANSR	74LV74A
	SSOP – DB	Reel of 2000	SN74LV74ADBR	LV74A
	TSSOP – PW	Tube of 90	SN74LV74APW	LV74A
		Reel of 2000	SN74LV74APWR	
Reel of 250		SN74LV74APWT		
TVSOP – DGV	Reel of 2000	SN74LV74ADGVR	LV74A	
–55°C to 125°C	CDIP – J	Tube of 25	SNJ54LV74AJ	SNJ54LV74AJ
	CFP – W	Tube of 150	SNJ54LV74AW	SNJ54LV74AW
	LCCC – FK	Tube of 55	SNJ54LV74AFK	SNJ54LV74AFK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



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**TEXAS  
INSTRUMENTS**

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# SN54LV74A, SN74LV74A DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOPS

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## recommended operating conditions (see Note 5)

		SN54LV74A		SN74LV74A		UNIT
		MIN	MAX	MIN	MAX	
$V_{CC}$	Supply voltage	2	5.5	2	5.5	V
$V_{IH}$	High-level input voltage	$V_{CC} = 2\text{ V}$	1.5	1.5		V
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	$V_{CC} \times 0.7$	$V_{CC} \times 0.7$		
		$V_{CC} = 3\text{ V to }3.6\text{ V}$	$V_{CC} \times 0.7$	$V_{CC} \times 0.7$		
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	$V_{CC} \times 0.7$	$V_{CC} \times 0.7$		
$V_{IL}$	Low-level input voltage	$V_{CC} = 2\text{ V}$		0.5	0.5	V
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$		$V_{CC} \times 0.3$	$V_{CC} \times 0.3$	
		$V_{CC} = 3\text{ V to }3.6\text{ V}$		$V_{CC} \times 0.3$	$V_{CC} \times 0.3$	
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$		$V_{CC} \times 0.3$	$V_{CC} \times 0.3$	
$V_I$	Input voltage	0	5.5	0	5.5	V
$V_O$	Output voltage	0	$V_{CC}$	0	$V_{CC}$	V
$I_{OH}$	High-level output current	$V_{CC} = 2\text{ V}$		-50	-50	$\mu\text{A}$
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$		-2	-2	mA
		$V_{CC} = 3\text{ V to }3.6\text{ V}$		-6	-6	
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$		-12	-12	
$I_{OL}$	Low-level output current	$V_{CC} = 2\text{ V}$		50	50	$\mu\text{A}$
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$		2	2	mA
		$V_{CC} = 3\text{ V to }3.6\text{ V}$		6	6	
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$		12	12	
$\Delta t/\Delta v$	Input transition rise or fall rate	$V_{CC} = 2.3\text{ V to }2.7\text{ V}$		200	200	ns/V
		$V_{CC} = 3\text{ V to }3.6\text{ V}$		100	100	
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$		20	20	
$T_A$	Operating free-air temperature	-55	125	-40	85	$^{\circ}\text{C}$

NOTE 5: All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	$V_{CC}$	SN54LV74A			SN74LV74A			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
$V_{OH}$	$I_{OH} = -50\ \mu\text{A}$	2 V to 5.5 V	$V_{CC}-0.1$			$V_{CC}-0.1$			V
	$I_{OH} = -2\ \text{mA}$	2.3 V	2			2			
	$I_{OH} = -6\ \text{mA}$	3 V	2.48			2.48			
	$I_{OH} = -12\ \text{mA}$	4.5 V	3.8			3.8			
$V_{OL}$	$I_{OL} = 50\ \mu\text{A}$	2 V to 5.5 V	0.1			0.1			V
	$I_{OL} = 2\ \text{mA}$	2.3 V	0.4			0.4			
	$I_{OL} = 6\ \text{mA}$	3 V	0.44			0.44			
	$I_{OL} = 12\ \text{mA}$	4.5 V	0.55			0.55			
$I_I$	$V_I = 5.5\ \text{V or GND}$	0 to 5.5 V	$\pm 1$			$\pm 1$			$\mu\text{A}$
$I_{CC}$	$V_I = V_{CC}\ \text{or GND, } I_O = 0$	5.5 V	20			20			$\mu\text{A}$
$I_{off}$	$V_I\ \text{or } V_O = 0\ \text{to } 5.5\ \text{V}$	0	5			5			$\mu\text{A}$
$C_i$	$V_I = V_{CC}\ \text{or GND}$	3.3 V	2			2			pF
		5 V	2			2			

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



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# SN54LV74A, SN74LV74A DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOPS

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**timing requirements over recommended operating free-air temperature range,  $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$  (unless otherwise noted) (see Figure 1)**

PARAMETER			$T_A = 25^\circ\text{C}$		SN54LV74A		SN74LV74A		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
$t_w$	Pulse duration	PRE or CLR low	8		9		9		ns
		CLK	8		9		9		
$t_{su}$	Setup time before CLK $\uparrow$	Data	8		9		9		ns
		PRE or CLR inactive	7		7		7		
$t_h$	Hold time, data after CLK $\uparrow$		0.5		0.5		0.5		ns

**timing requirements over recommended operating free-air temperature range,  $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$  (unless otherwise noted) (see Figure 1)**

PARAMETER			$T_A = 25^\circ\text{C}$		SN54LV74A		SN74LV74A		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
$t_w$	Pulse duration	PRE or CLR low	6		7		7		ns
		CLK	6		7		7		
$t_{su}$	Setup time before CLK $\uparrow$	Data	6		7		7		ns
		PRE or CLR inactive	5		5		5		
$t_h$	Hold time, data after CLK $\uparrow$		0.5		0.5		0.5		ns

**timing requirements over recommended operating free-air temperature range,  $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$  (unless otherwise noted) (see Figure 1)**

PARAMETER			$T_A = 25^\circ\text{C}$		SN54LV74A		SN74LV74A		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
$t_w$	Pulse duration	PRE or CLR low	5		5		5		ns
		CLK	5		5		5		
$t_{su}$	Setup time before CLK $\uparrow$	Data	5		5		5		ns
		PRE or CLR inactive	3		3		3		
$t_h$	Hold time, data after CLK $\uparrow$		0.5		0.5		0.5		ns

**switching characteristics over recommended operating free-air temperature range,  $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$  (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN54LV74A		SN74LV74A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$f_{max}$			$C_L = 15\text{ pF}$	50*	100*		40*		40	MHz	
			$C_L = 50\text{ pF}$	30	70		25		25		
$t_{pd}$	PRE or CLR	Q or $\bar{Q}$	$C_L = 15\text{ pF}$	9.8*	14.8*		1*	17*	1	17	ns
	CLK			11.1*	16.4*		1*	19*	1	19	
$t_{pd}$	PRE or CLR	Q or $\bar{Q}$	$C_L = 50\text{ pF}$	13	17.4		1	20	1	20	ns
	CLK			14.2	20		1	23	1	23	

\* On products compliant to MIL-PRF-38535, this parameter is not production tested.

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



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# SN54LV74A, SN74LV74A DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOPS

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switching characteristics over recommended operating free-air temperature range,  $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN54LV74A		SN74LV74A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$f_{\text{max}}$			$C_L = 15\text{ pF}$	80*	140*		70*		70		MHz
			$C_L = 50\text{ pF}$	50	90		45		45		
$t_{\text{pd}}$	PRE or CLR	Q or $\bar{Q}$	$C_L = 15\text{ pF}$		6.9*	12.3*	1*	14.5*	1	14.5	ns
	CLK				7.9*	11.9*	1*	14*	1	14	
$t_{\text{pd}}$	PRE or CLR	Q or $\bar{Q}$	$C_L = 50\text{ pF}$		9.2	15.8	1	18	1	18	ns
	CLK				10.2	15.4	1	17.5	1	17.5	

\* On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range,  $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN54LV74A		SN74LV74A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$f_{\text{max}}$			$C_L = 15\text{ pF}$	130*	180*		110*		110		MHz
			$C_L = 50\text{ pF}$	90	140		75		75		
$t_{\text{pd}}$	PRE or CLR	Q or $\bar{Q}$	$C_L = 15\text{ pF}$		5*	7.7*	1*	9*	1	9	ns
	CLK				5.6*	7.3*	1*	8.5*	1	8.5	
$t_{\text{pd}}$	PRE or CLR	Q or $\bar{Q}$	$C_L = 50\text{ pF}$		6.6	9.7	1	11	1	11	ns
	CLK				7.2	9.3	1	10.5	1	10.5	

\* On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics,  $V_{CC} = 3.3\text{ V}$ ,  $C_L = 50\text{ pF}$ ,  $T_A = 25^\circ\text{C}$  (see Note 6)

PARAMETER		SN74LV74A			UNIT
		MIN	TYP	MAX	
$V_{OL(P)}$	Quiet output, maximum dynamic $V_{OL}$		0.1	0.8	V
$V_{OL(V)}$	Quiet output, minimum dynamic $V_{OL}$		0	-0.8	V
$V_{OH(V)}$	Quiet output, minimum dynamic $V_{OH}$		3.2		V
$V_{IH(D)}$	High-level dynamic input voltage	2.31			V
$V_{IL(D)}$	Low-level dynamic input voltage		0.99		V

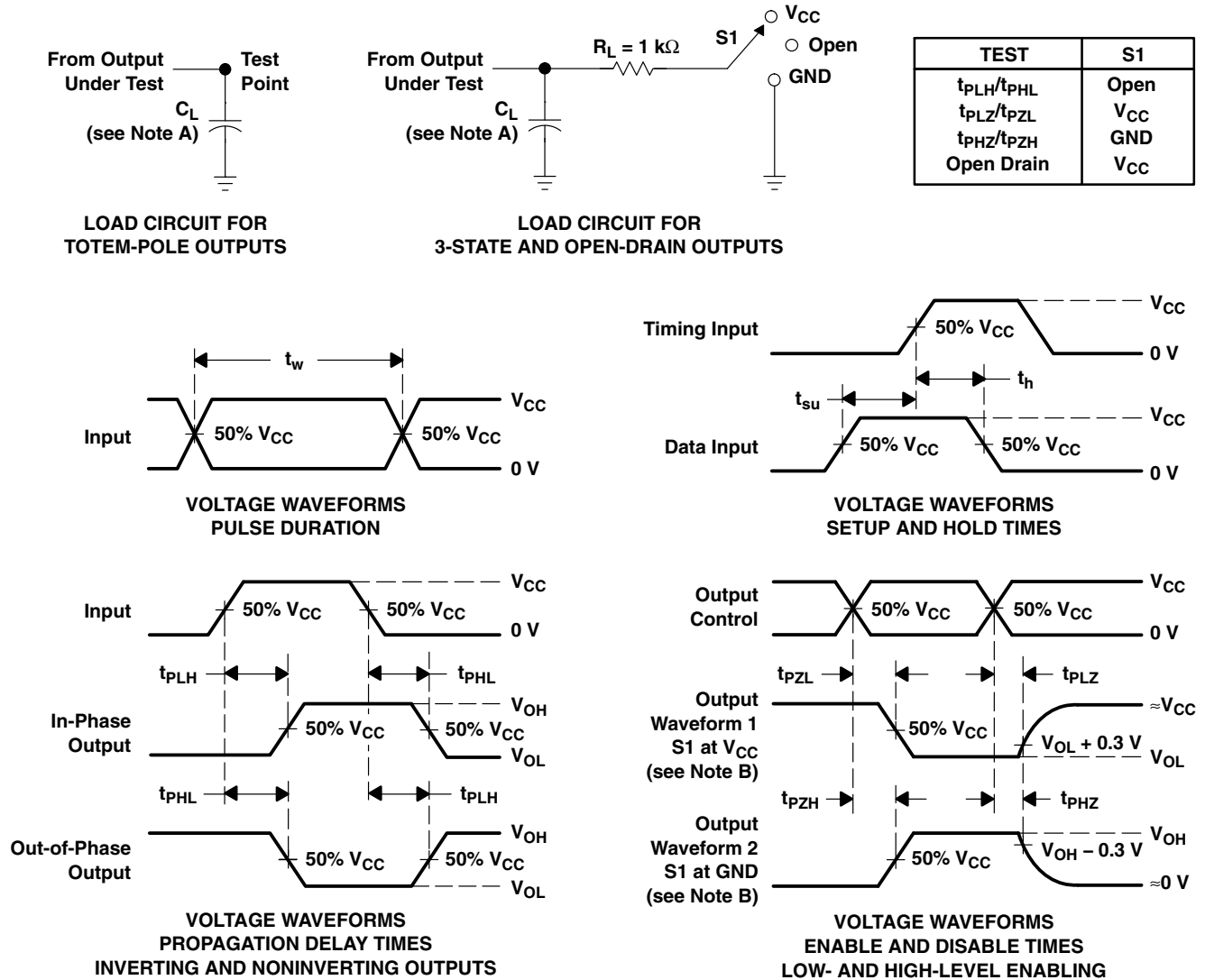
NOTE 6: Characteristics are for surface-mount packages only.

operating characteristics,  $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	$V_{CC}$	TYP	UNIT
$C_{\text{pd}}$	Power dissipation capacitance	$C_L = 50\text{ pF}$ , $f = 10\text{ MHz}$	3.3 V	21	pF
			5 V	23	



**PARAMETER MEASUREMENT INFORMATION**



- NOTES:
- A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq 1\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r \leq 3\text{ ns}$ ,  $t_f \leq 3\text{ ns}$ .
  - D. The outputs are measured one at a time, with one input transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G.  $t_{PHL}$  and  $t_{PLH}$  are the same as  $t_{pd}$ .
  - H. All parameters and waveforms are not applicable to all devices.

**Figure 1. Load Circuit and Voltage Waveforms**

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74LV74AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV74ADBLE	OBSOLETE	SSOP	DB	14		TBD	Call TI	Call TI
SN74LV74ADBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV74ADBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV74ADBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV74ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV74ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV74ADGVR	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV74ADGVRE4	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV74ADGVRG4	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV74ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV74ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV74ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV74ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV74ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV74APW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV74APWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV74APWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV74APWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI
SN74LV74APWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV74APWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV74APWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV74APWT	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV74APWTE4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV74APWTG4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV74ARGYR	ACTIVE	VQFN	RGY	14	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
						no Sb/Br)		
SN74LV74ARGYRG4	ACTIVE	VQFN	RGY	14	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**OTHER QUALIFIED VERSIONS OF SN74LV74A :**

- Automotive: [SN74LV74A-Q1](#)
- Enhanced Product: [SN74LV74A-EP](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV74ADBR	SSOP	DB	14	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74LV74ADGVR	TVSOP	DGV	14	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74LV74ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LV74ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LV74APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV74APWR	TSSOP	PW	14	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1
SN74LV74APWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV74APWT	TSSOP	PW	14	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV74ARGYR	VQFN	RGY	14	3000	330.0	12.4	3.75	3.75	1.15	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV74ADBR	SSOP	DB	14	2000	346.0	346.0	33.0
SN74LV74ADGVR	TVSOP	DGV	14	2000	346.0	346.0	29.0
SN74LV74ADR	SOIC	D	14	2500	346.0	346.0	33.0
SN74LV74ANSR	SO	NS	14	2000	346.0	346.0	33.0
SN74LV74APWR	TSSOP	PW	14	2000	346.0	346.0	29.0
SN74LV74APWR	TSSOP	PW	14	2000	364.0	364.0	27.0
SN74LV74APWRG4	TSSOP	PW	14	2000	346.0	346.0	29.0
SN74LV74APWT	TSSOP	PW	14	250	346.0	346.0	29.0
SN74LV74ARGYR	VQFN	RGY	14	3000	346.0	346.0	29.0

DGV (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN

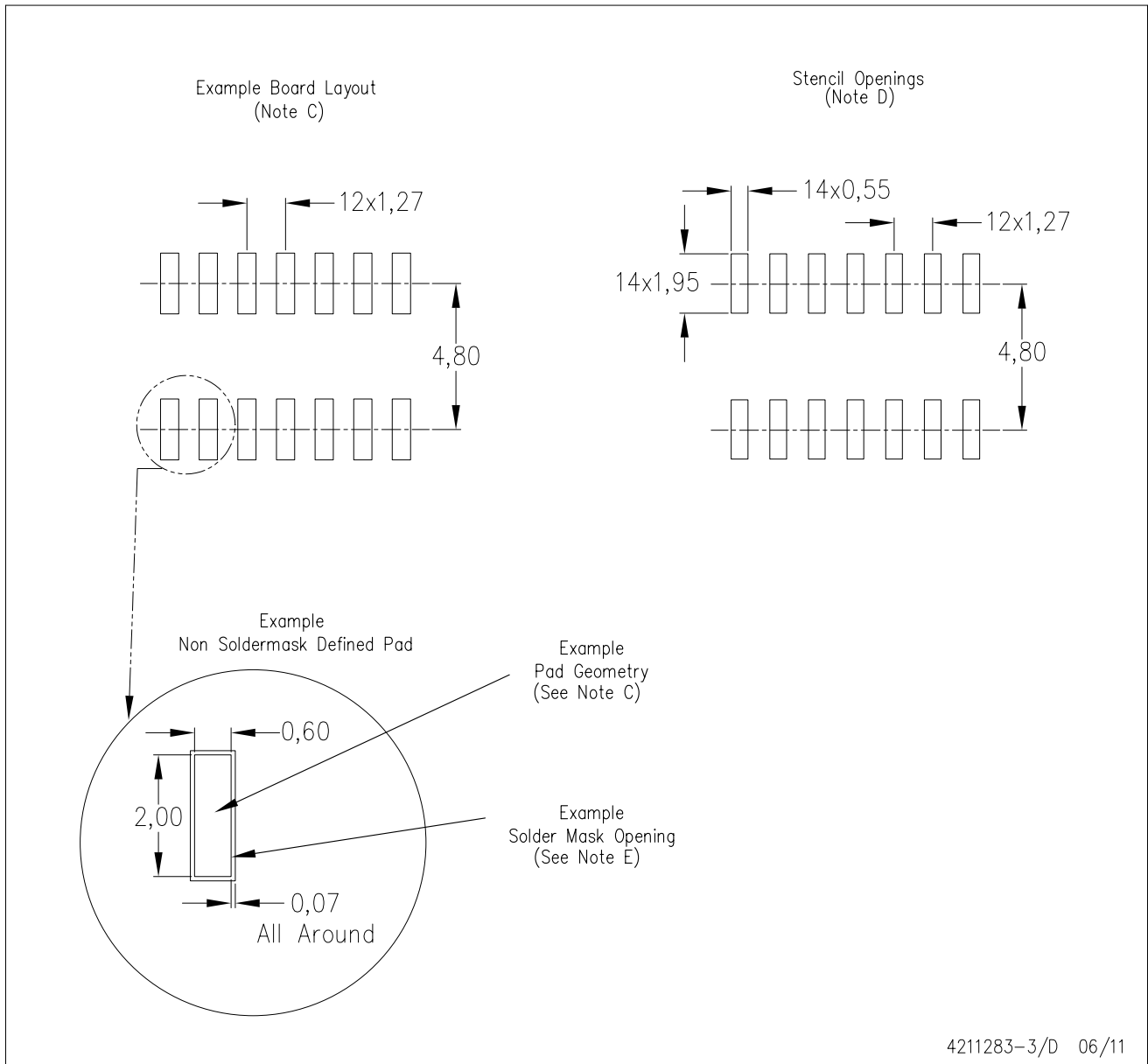


- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE

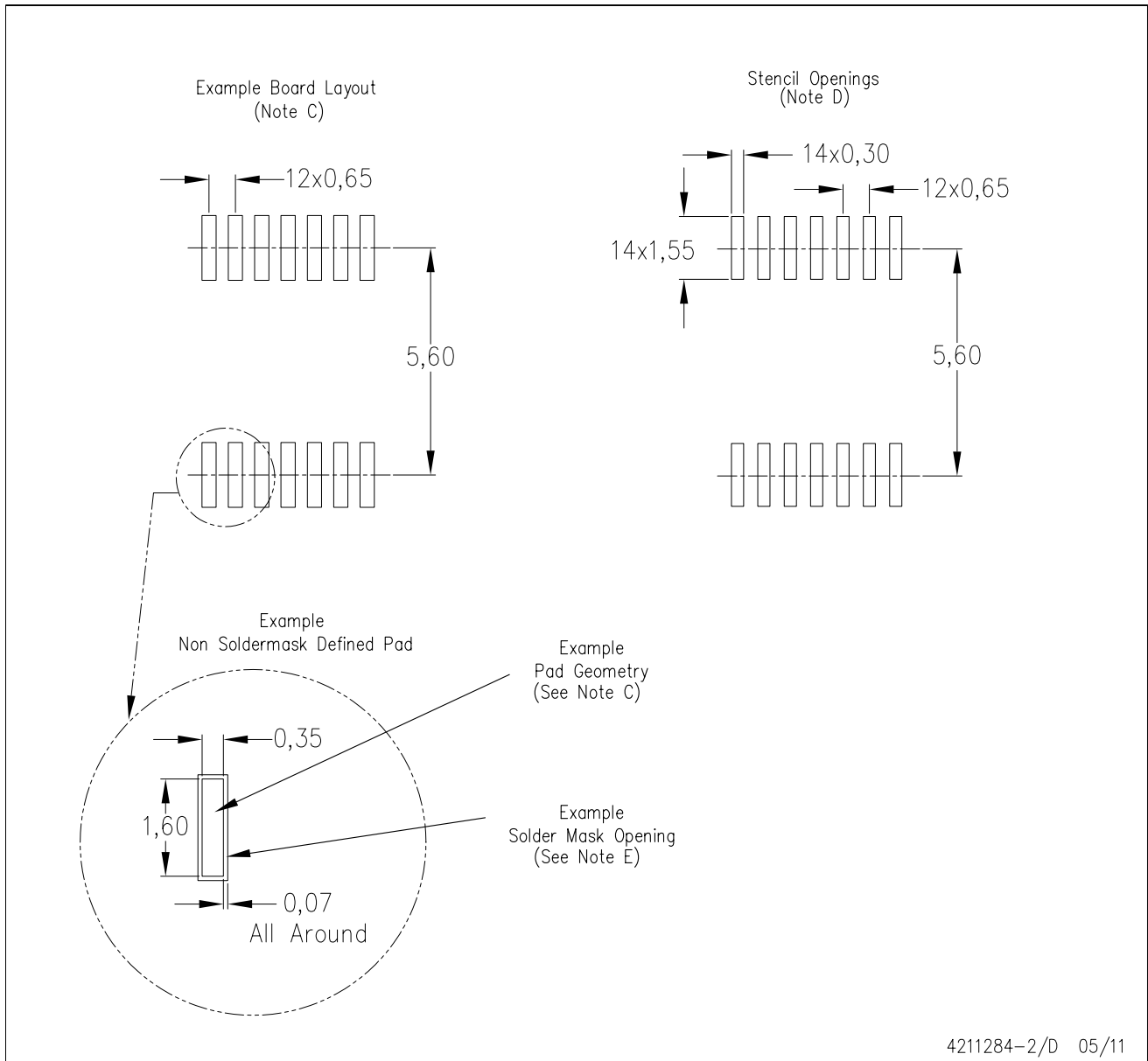


- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G14)

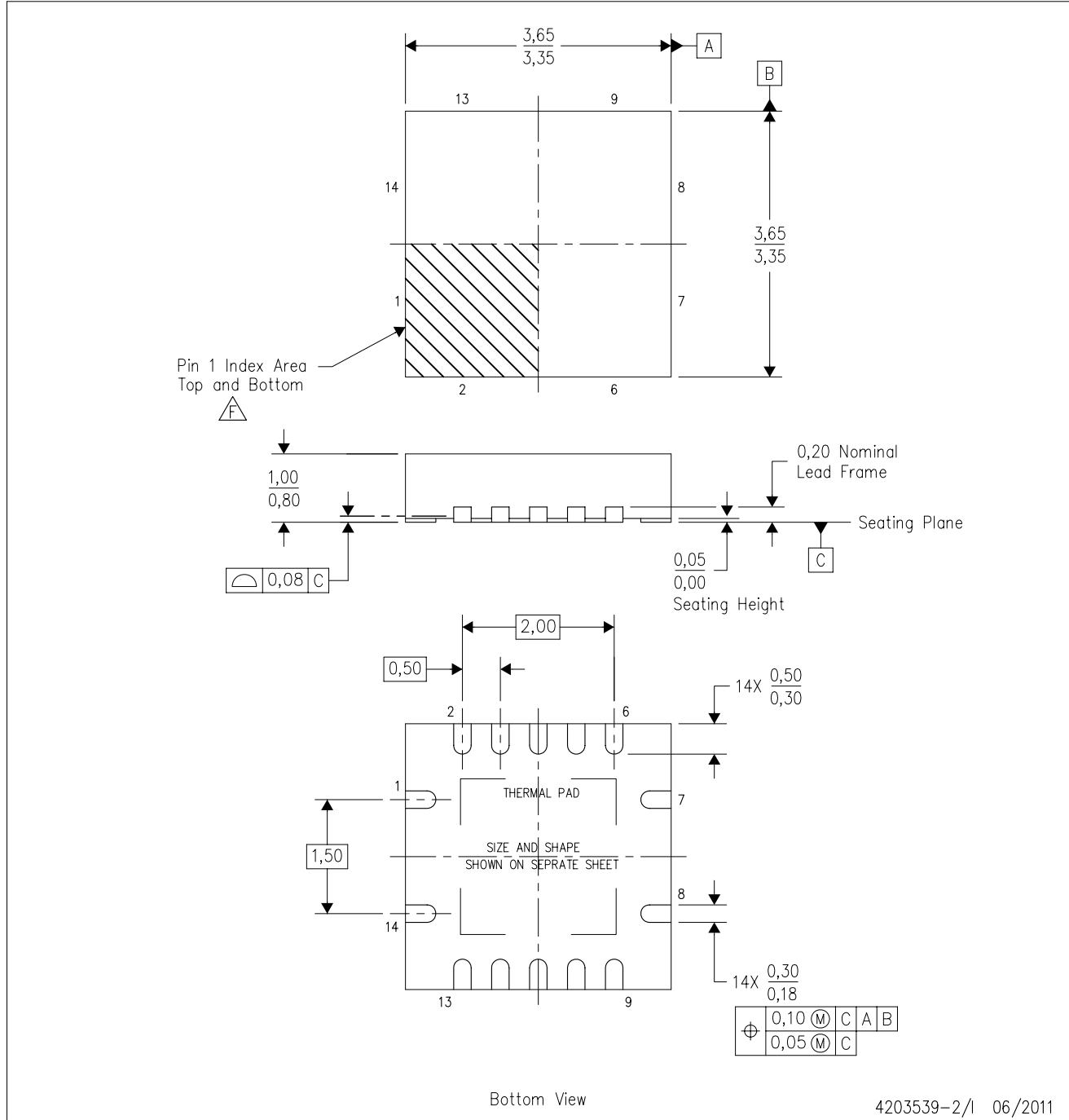
PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

RGY (S-PVQFN-N14)

PLASTIC QUAD FLATPACK NO-LEAD



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. QFN (Quad Flatpack No-Lead) package configuration.
  - D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
  - E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
  - F** Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
  - G. Package complies to JEDEC MO-241 variation BA.

RGY (S-PVQFN-N14)

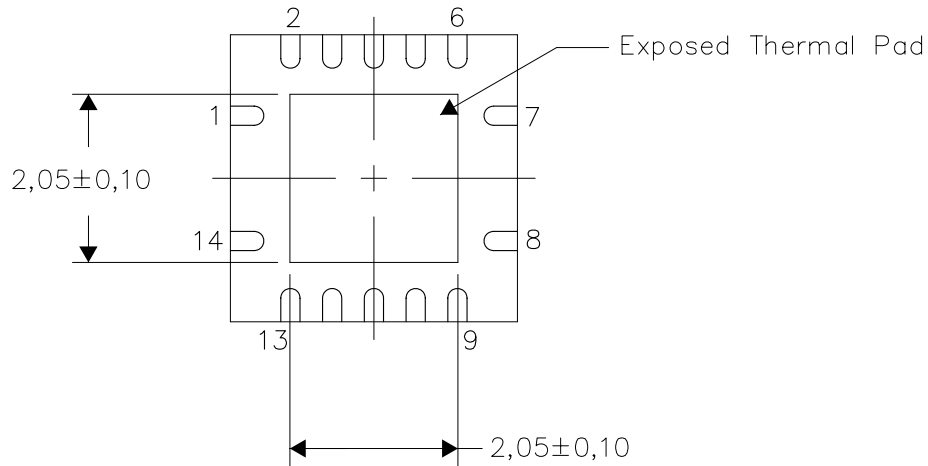
PLASTIC QUAD FLATPACK NO-LEAD

**THERMAL INFORMATION**

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at [www.ti.com](http://www.ti.com).

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

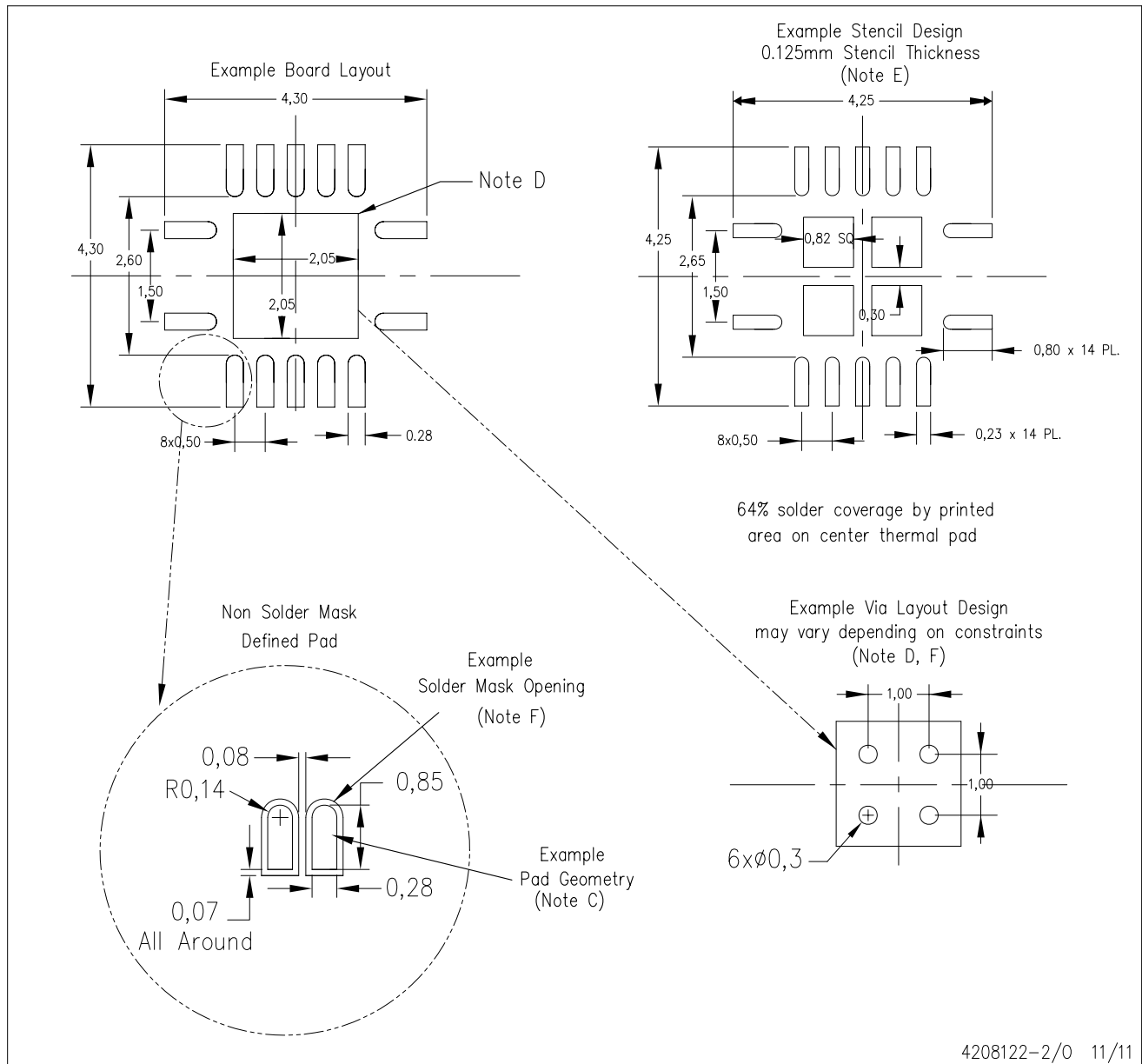
Exposed Thermal Pad Dimensions

4206353-2/0 11/11

NOTE: All linear dimensions are in millimeters

RGY (S-PVQFN-N14)

PLASTIC QUAD FLATPACK NO-LEAD



4208122-2/0 11/11

- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at [www.ti.com](http://www.ti.com) <<http://www.ti.com>>.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
  - Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

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